

TENTATIVE

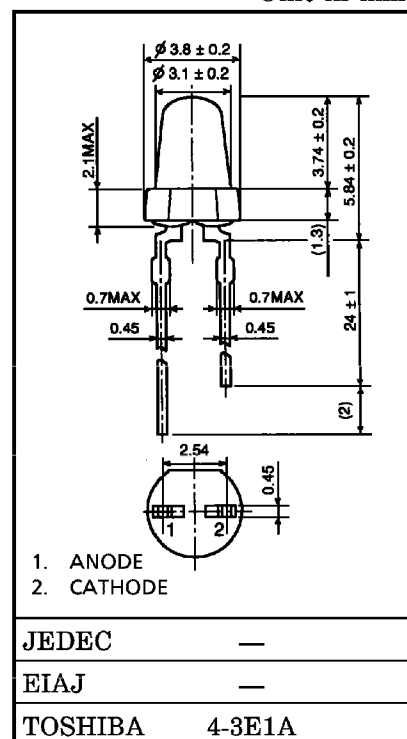
TOSHIBA LED LAMP InGaAlP GREEN LIGHT EMISSION

# TLGE160

## PANEL CIRCUIT INDICATOR

Unit in mm

- 3mm DIAMETER (T1-3/4)
- InGaAlP GREEN LED
- All Plastic Mold Type.
- Colorless Clear Lens
- Low Drive Current, High Intensity Green Light Emission  
Recommended Forward Current :  $I_F = 15 \sim 20\text{mA}$  (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- High Power Luminous Intensity
- APPLICATIONS : Suitable for Outdoor Message Signboard, Safety equipment, etc.



## MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	$I_F$	50	mA
Reverse Voltage	$V_R$	4	V
Power Dissipation	$P_D$	140	mW
Operating Temperature Range	$T_{opr}$	-30~85	°C
Storage Temperature Range	$T_{stg}$	-40~120	°C

Weight : 0.31g

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## ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	—	2.27	2.8	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =4V	—	—	50	μA
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> =20mA (Note)	850	3000	—	mcd
Peak Emission Wavelength	λ <sub>p</sub>	I <sub>F</sub> =20mA	—	574	—	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> =20mA	—	11	—	nm
Dominant Wavelength	λ <sub>d</sub>	I <sub>F</sub> =20mA	—	571	—	nm

(Note) Rank selection carried out under next range respectively, although it needs ±15% additional for guaranteed limits.

S : 1000-2000mcd, T : 1800-3600mcd, U : 3200-6400mcd.

## PRECAUTION

Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.  
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

